



## Material Content Data Sheet



<b>Sales Product Name</b>		BSL802SN H6327		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001165078						
<b>Package</b>		PG-TSOP6-6-6		<b>Weight*</b>		13.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.010	0.07		723	
	noble metal	gold	7440-57-5	0.038	0.28		2803	
	inorganic material	silicon	7440-21-3	0.583	4.28	4.63	42760	46286
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		433	
	non noble metal	chromium	7440-47-3	0.018	0.13		1299	
	non noble metal	copper	7440-50-8	5.882	43.11	43.29	431068	432887
wire	non noble metal	copper	7440-50-8	0.066	0.48	0.48	4810	4810
encapsulation	organic material	carbon black	1333-86-4	0.066	0.48		4812	
	plastics	epoxy resin	-	1.412	10.35		103456	
	inorganic material	silicondioxide	60676-86-0	5.089	37.29	48.12	372924	481192
leadfinish	non noble metal	tin	7440-31-5	0.299	2.19	2.19	21905	21905
plating	noble metal	silver	7440-22-4	0.176	1.29	1.29	12920	12920
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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